

## ATTACHMENT 1(f)

LIST OF COPENDING APPLICATIONS	ATTORNEY DOCKET NO.	APPLICATION NO.
	SH-19698-US	
	FIRST NAMED INVENTOR	
	Hyun-Kwan Chung et al.	
FILING DATE	GROUP ART UNIT	
March 30, 2004		

The following, prior-filed, copending U.S. patent application(s) is/are listed in accordance with the duty of disclosure provisions of 37 CFR § 1.56, so that the Examiner may consider same should he deem any thereof to be material to examination of the subject application. Pursuant to 37 CFR 1.98(a)(2)(iii), a copy of the identified copending application(s) is provided.

It is requested that the Examiner acknowledge his consideration of application(s) below-listed by initialing same in the space provided adjacent each such application and that the Examiner sign and date this form at the bottom thereof to confirm such consideration having been given.

**This submission in no way represents an admission that any of the information listed herein constitutes prior art with respect to the subject application and unless and until such prior art status is established, this submission is not a request that the information presented herein be printed on the face of any patent issuing from the subject application in which this information is being filed.**

## U.S. PATENT APPLICATION DOCUMENTS

*EXAMINER INITIAL		U.S. SERIAL NO.	FILING DATE	NAME	ASSIGNEE
/H.N./	1	10/647,445	August 26, 2003	Jung et al.	Samsung Electronics Co., Ltd.
/H.N./	2	10/165,427 (Published as (2003/0012558)	June 10, 2002	Kim et al.	Samsung Electronics Co., Ltd.
/H.N./	3	10/170,419 (Published as 2003/0049017)	June 14, 2003	Chung et al	Samsung Electronics Co., Ltd.
/H.N./	4	10/277,094 (Published as 2003/0084460)	October 22, 2002	Chung et al	Samsung Electronics Co., Ltd.
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EXAMINER	DATE CONSIDERED
/Huy Nguyen/	08/30/2008

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.